1.8V/2.5V/3.3V 8GHz / 14Gbps Differential 1:4 Clock / Data CML Fanout Buffer w/ Selectable Input Equalizer

Multi-Level Inputs w/ Internal Termination

Description

The NB7VQ14M is a high performance differential 1:4 CML fanout buffer with a selectable Equalizer receiver. When placed in series with a Clock /Data path operating up to 8 GHz or 14 Gb/s, respectively, the NB7VQ14M inputs will compensate the degraded signal transmitted across a FR4 PCB backplane or cable interconnect and output four identical CML copies of the input signal with a 1.8 V, 2.5 V or 3.3 V power supply. Therefore, the serial data rate is increased by reducing Inter-Symbol Interference (ISI) caused by losses in copper interconnect or long cables. The EQualizer ENable pin (EQEN) allows the IN/IN inputs to either flow through or bypass the Equalizer section. Control of the Equalizer function is realized by setting EQEN; When EQEN is set Low, the IN/IN inputs bypass the Equalizer. When EQEN is set High, the IN/IN inputs flow through the Equalizer. The default state at start-up is LOW. As such, NB7VQ14M is ideal for SONET, GigE, Fiber Channel, Backplane and other Clock/Data distribution applications.

The differential inputs incorporate internal 50 Ω termination resistors that are accessed through the VT pin. This feature allows the NB7VQ14M to accept various logic level standards, such as LVPECL, CML or LVDS. The 1:4 fanout design was optimized for low output skew applications.

The NB7VQ14M is a member of the GigaComm[™] family of high performance clock products.

Features

- Input Data Rate > 14 Gb/s, Typical
- Input Clock Frequency > 8 GHz, Typical
- 165 ps Typical Propagation Delay
- 30 ps Typical Rise and Fall Times
- < 15 ps Maximum Output Skew
- < 0.8 ps Maximum RMS Clock Jitter
- < 10 ps pp of Data Dependent Jitter
- Differential CML Outputs, 400 mV Peak-to-Peak, Typical
- Selectable Input Equalization
- Operating Range: $V_{CC} = 1.71$ V to 3.6 V with GND = 0 V
- Internal Input Termination Resistors, 50 Ω
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



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*For additional marking information, refer to Application Note AND8002/D.





ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.







Figure 2. QFN-16 Pinout (Top View)

Table 2. PIN DESCRIPTION

Table 1. EQUALIZER ENABLE FUNCTION

EQEN	Function			
0	IN / \overline{IN} Inputs By–pass the Equalizer section			
1	Inputs flow through the Equalizer			

Pin	Name	I/O	Description	
1	IN	LVPECL, CML, LVDS Input	Non-inverted Differential Input. Note 1.	
2	VT		Internal 100 Ω Center-tapped Termination Pin for IN / $\overline{\text{IN}}$	
3	VREFAC		Output Voltage Reference for Capacitor-Coupled Inputs, only	
4	ĪN	LVPECL, CML, LVDS Input	Inverted Differential Input. Note 1.	
5	EQEN	LVCMOS Input	Equalizer Enable Input; pin will default LOW when left open (has internal pull-down resistor)	
6	<u>Q3</u>	CML Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to $V_{CC}.$	
7	Q3	CML Output	Non-inverted Differential Output. Typically Terminated with 50 Ω Resistor to V $_{CC}$	
8	VCC	-	Positive Supply Voltage	
9	Q2	CML Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V $_{CC}$.	
10	Q2	CML Output	Non-inverted Differential Output. Typically Terminated with 50 Ω Resistor to V $_{CC}$	
11	Q1	CML Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V $_{CC}$	
12	Q1	CML Output	Non-inverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} .	
13	VCC	-	Positive Supply Voltage	
14	<u>Q0</u>	CML Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} .	
15	Q0	CML Output	Non-inverted Differential Output. Typically Terminated with 50 Ω Resistor to V $_{CC}$	
16	GND	-	Negative Supply Voltage	
I	EP	-	The Exposed Pad (EP) on the QFN-16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to the die, and must be electrically and thermally connected to GND on the PC board.	

 In the differential configuration when the input termination pin (VT) is connected to a common termination voltage or left open, and if no signal is applied on IN / IN input, then, the device will be susceptible to self–oscillation.

2. All VCC and GND pins must be externally connected to a power supply for proper operation.

Table 3. ATTRIBUTES

Characteristic	Value				
ESD Protection Human Body Model Machine Model		> 2 kV > 200V			
R _{PD} – EQEN Input Pulldown Resistor	75 kΩ				
Moisture Sensitivity (Note 3) 16–QFN		Level 1			
Flammability Rating	UL 94 V-0 @ 0.125 in				
Transistor Count	210				
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

3. For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply – Core	GND = 0 V		4.0	V
V _{IO}	Positive Input/Output Voltage	GND = 0 V		-0.5 to V _{CC} + 0.5	V
V _{INPP}	Differential Input Voltage IN – IN			1.89	V
I _{IN}	Input Current Through R_T (50 Ω Resistor)			±40	mA
I _{OUT}	Output Current Through R_T (50 Ω Resistor)			±40	mA
IVFREFAC	VREFAC Sink/Source Current			±1.5	mA
T _A	Operating Temperature Range	16 QFN		-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient) (Note 4)	0 lfpm 500 lfpm	16 QFN 16 QFN	42 35	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case) (Note 4)		16 QFN	4	°C/W
T _{sol}	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

4. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS, MULTI-LEVEL INPUTS V_{CC} = 1.71 V to 3.6 V; GND = 0 V;

 $T_A = -40^{\circ}C$ to $85^{\circ}C$ (Note 5)

Symbol	Characteristic		Min	Тур	Max	Uni
POWER S	UPPLY CURRENT					
V _{CC}	Power Supply Voltage	V _{CC} = 3.3 V V _{CC} = 2.5 V V _{CC} = 1.8 V	3.135 2.375 1.71	3.3 2.5 1.8	3.6 2.625 1.89	V
I _{CC}	Power Supply Current (Inputs and Outputs Open)			170	210	mA
CML OUT	PUTS (Note 6)					
V _{OH}	Output HIGH Voltage	V _{CC} = 3.3 V V _{CC} = 2.5 V V _{CC} = 1.8 V	V _{CC} - 30 3270 2470 1770	V _{CC} – 5 3295 2495 1795	V _{CC} 3300 2500 1800	mV
V _{OL}	Output LOW Voltage	V _{CC} = 3.3 V V _{CC} = 2.5 V V _{CC} = 1.8 V	V _{CC} – 525 2775 1975 1275	V _{CC} – 425 2875 2075 1375	V _{CC} - 325 2975 2175 1475	mV
DIFFEREN	NTIAL INPUT DRIVEN SINGLE-ENDED (see Figures 5	and 7) (Note 7)		•		
V _{IH}	Single-ended Input HIGH Voltage		V _{th} + 100		V _{CC}	mV
V _{IL}	Single-ended Input LOW Voltage		GND		V _{th} –100	mV
V _{th}	Input Threshold Reference Voltage Range (Note 8)		1050		V _{CC} – 100	mV
VISE	Single-ended Input Voltage Amplitude (VIH - VIL)		200		2800	mV
VREFAC						
V _{REFAC}	$ \begin{array}{c c} Output Reference Voltage @ 100 \ \mu A \ for \ capacitor - \ coupled \ inputs, \\ only \ (Note \ 9) & V_{CC} = 3.3 \ V \\ V_{CC} = 2.5 \ V \\ V_{CC} = 1.8 \ V \end{array} $		V _{CC} – 650 2650 1850 1150	V _{CC} - 500 2800 2000 1300	V _{CC} - 350 2950 2150 1450	mV
DIFFEREN	ITIAL INPUTS DRIVEN DIFFERENTIALLY (see Figure	s 6 and 8) (Note 9)				
V _{IHD}	Differential Input HIGH Voltage		1200		V _{CC}	mV
V _{ILD}	Differential Input LOW Voltage		0		V _{IHD} – 100	mV
V _{ID}	Differential Input Voltage (V _{IHD} – V _{ILD})		100		1200	m۷
V _{CMR}	Input Common Mode Range (Differential Configuration) (Note 10) (Figure 9)		1050		V _{CC} – 50	mV
I _{IH}	Input HIGH Current IN / IN, (VT Open)		-150		150	μA
I _{IL}	Input LOW Current IN / IN, (VT Open)		-150		150	μA
CONTROL	- INPUTS (EQEN)					
VIH	Input HIGH Voltage for Control Pins		V _{CC} x 0.65		V _{CC}	V
V _{IL}	Input LOW Voltage for Control Pins		GND		V _{CC} x 0.35	V
I _{IH}	Input HIGH Current		-150		150	μA
IIL	Input LOW Current		-150		150	μA
TERMINA	TION RESISTORS					
R _{TIN}	Internal Input Termination Resistor		45	50	55	Ω
	Internal Output Termination Resistor		45	50	55	Ω

operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
Input and output parameters vary 1:1 with V_{CC}.
CML outputs loaded with 50 Ω to V_{CC} for proper operation.
V_{th}, V_{IH}, V_{IL}, and V_{ISE} parameters must be complied with simultaneously.
V_{th} is applied to the complementary input when operating in single-ended mode.
V_{IHD}, V_{ILD}, V_{ID} and V_{CMR} parameters must be complied with simultaneously.
I. V_{CMR} min varies 1:1 with GND, V_{CMR} max varies 1:1 with V_{CC}. The V_{CMR} range is referenced to the crosspoint side of the differential input signal.

Symbol	Characteristic		Min	Тур	Max	Unit
f _{MAX}	Maximum Input Clock Frequency; V _C	$_{\rm OUT} \ge 200 \ {\rm mV}$	7	8.5		GHz
f _{DATAMAX}	Maximum Operating Data Rate NRZ, (PRBS23)		10	14		Gbps
V _{OUTPP}	Output Voltage Amplitude, EQEN = 0 or 1 (Note 15) (See Figure 10)	f _{in} ≤ 7GHz	200	400		mV
t _{PLH} , t _{PHL}	Propagation Delay	IN to $Q_{\rm x}$	125	175	225	ps
t _{SKEW}	Duty Cycle Skew (Note 12) Output – Output Within Device Skew Device to Device Skew			3	15 15 50	ps
t _{DC}	Output Clock Duty Cycle (Reference Duty Cycle = 50%)	$f_{in} \le 7GHz$	40	50	60	%
$\Phi_{\sf N}$	Phase Noise, fin = 1 GHz	10 kHz 100 kHz 1 MHz 10 MHz 20 MHz 40 MHz		-134 -136 -150 -151 -151 -151		dBc
t _{∫ΦN}	Integrated Phase Jitter f _{in} = 1 GHz, 12 kHz – 20 MHz Offset (RMS)			35		fs
^t JITTER	RMS Random Clock Jitter (Note 13) Peak-to-Peak Data Dependent Jitter (Note 14) $f_{IN} \le 14$ Gbps EQEN = $f_{IN} \le 10$ Gbps EQEN			0.2	0.8 10 10	ps rms ps pk-pk ps pk-pk
V _{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 15)		100		1200	mV
t _r t _f	Output Rise/Fall Times @ 1.0 GHz (20% – 80%)	Qx, Qx	15	30	45	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. Measured by forcing V_{INPP} 400mV from a 50% duty cycle clock source. All loading with an external $R_L = 50 \Omega$ to V_{CC}. Input edge rates 40 ps (20% - 80%).

12. Skew is measured between outputs under identical transitions and conditions @ 0.5 GHz. Duty cycle skew is measured between differential outputs using the deviations of the sum of Tpw- and Tpw+ @ 0.5 GHz.

13. Additive RMS jitter with 50% duty cycle clock signal.

14. Additive peak-to-peak data dependent jitter with input NRZ data at PRBS23.

15. Input and output voltage swings are single-ended measurements operating in a differential mode.



Figure 3. CLOCK Output Voltage Amplitude (V_{OUTPP}) vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)







































Figure 14. Capacitor–Coupled Differential Interface (V_T Connected to V_{REFAC})

*V_{REFAC} bypassed to ground with a 0.01 μF capacitor





Figure 16. Typical CML Output Structure and Termination



Figure 17. Typical NB7VQ14M Equalizer Application and Interconnect with PRBS23 pattern at 6.5 Gbps, EQEN = 1

ORDERING INFORMATION

Device	Package	Shipping [†]
NB7VQ14MMNG	QFN-16 (Pb-Free)	123 Units / Rail
NB7VQ14MMNHTBG	QFN-16 (Pb-Free)	100 / Tape & Reel
NB7VQ14MMNTXG	QFN-16 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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